

Title (en)
PREPARING A SUBSTRATE FOR EMBEDDING WIRE

Title (de)
HERSTELLUNG EINES SUBSTRATS ZUM EINBETTEN EINES DRAHTES

Title (fr)
PRÉPARATION D'UN SUBSTRAT EN VUE D'Y INTÉGRER UN FIL

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Application
EP 12728426 A 20120529

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Abstract (en)
[origin: WO2012168106A1] The surface of a substrate (302; FIGs. 3C,3D,3E,3F,3G,3H; 4G) may be prepared for mounting an antenna wire (310) such as by removing material to form a sequence of ditches (holes) separated by bridges (lands), and conforming to a pattern (110) for the antenna, which is typically a flat squared spiral, having a number of turns. The antenna wire may be laid in the ditches and embedded in the bridges. Additional features, such as undermining (FIG. 3H) or removing material from adjacent (FIG. 4G, 4H) the bridges may facilitate displacement of substrate material at the bridges. The collapsed bridges form pinch points (FIG. 3E), securing the wire in the substrate. In some embodiments of the invention, relevant portions of the substrate are prepared for embedding antenna wire, without removing material. The substrate may be an inlay substrate or card body for a secure document.

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